

ABSTRACT OF THE DISCLOSURE

A manufacturing apparatus of a semiconductor device is provided with a pickup section for picking up a sectioned semiconductor element from a semiconductor wafer, a film sticking section for sticking an element adhesive film sectioned according to a shape of the element to the back surface of the semiconductor element, and an element adhesion section for adhering the semiconductor element to a semiconductor device forming base material. Chippings, which are caused when a thinned semiconductor wafer is diced, are suppressed so to reduce a failure incidence rate of the semiconductor device.